

### Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

### Product Summary

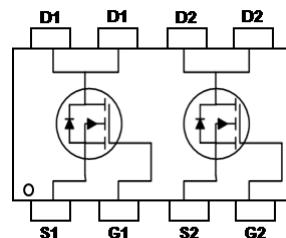
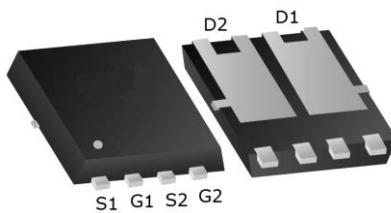
BVDSS	RDS(ON)	ID
30V	8.5mΩ	35A

### Description

The JHG3204 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most applications.

The JHG3204 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### DFN5X6 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1</sup>	35	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current <sup>1</sup>	24.7	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current <sup>1</sup>	10.6	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current <sup>1</sup>	8.5	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	92	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	57.8	mJ
I <sub>AS</sub>	Avalanche Current	34	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	19.2	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.42	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	6.5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=12\text{A}$	---	6.5	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	11	14	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	1.5	2.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=15\text{A}$	---	38	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.7	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=12\text{A}$	---	12.8	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	3.3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	6.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=12\text{A}$	---	4.5	---	$\text{ns}$
$T_r$	Rise Time		---	10.9	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	25.6	---	
$T_f$	Fall Time		---	9.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1317	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	163	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	131	---	

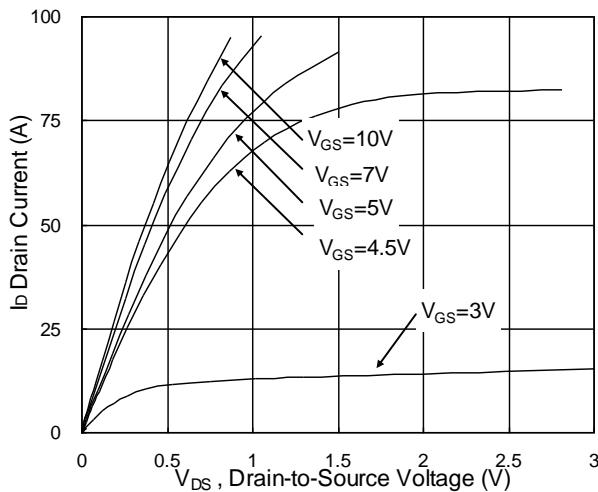
**Diode Characteristics**

$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	15	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=15\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	9.2	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	2	---	nC

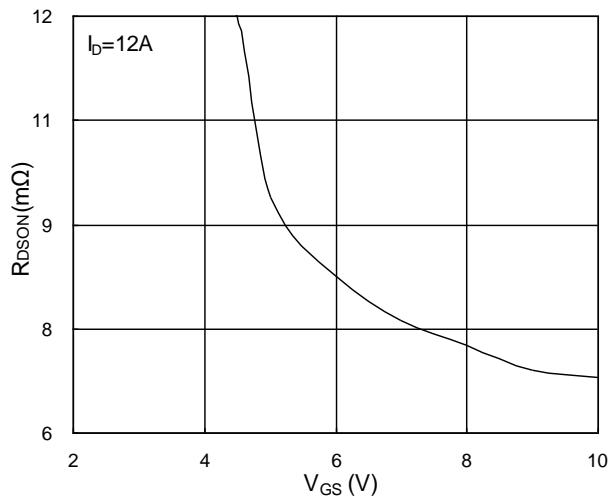
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=34\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_s$  , in real applications , should be limited by total power dissipation.

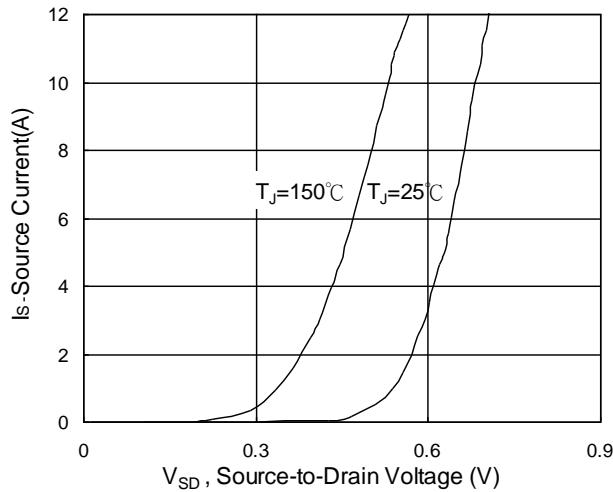
### Typical Characteristics



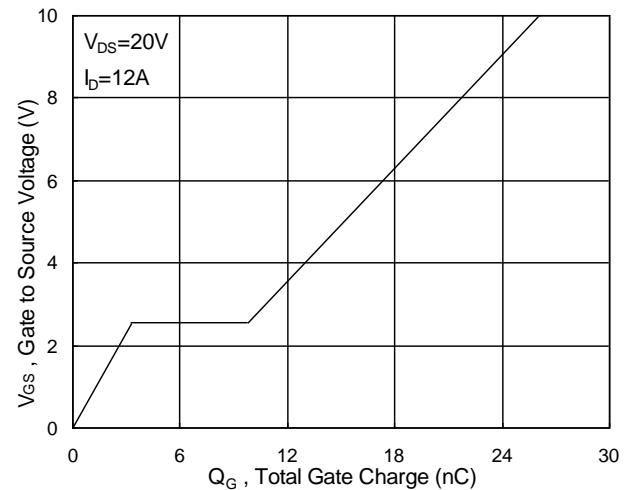
**Fig.1 Typical Output Characteristics**



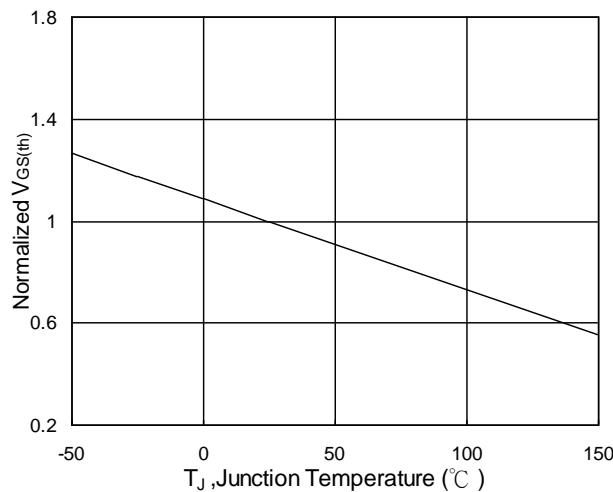
**Fig.2 On-Resistance vs G-S Voltage**



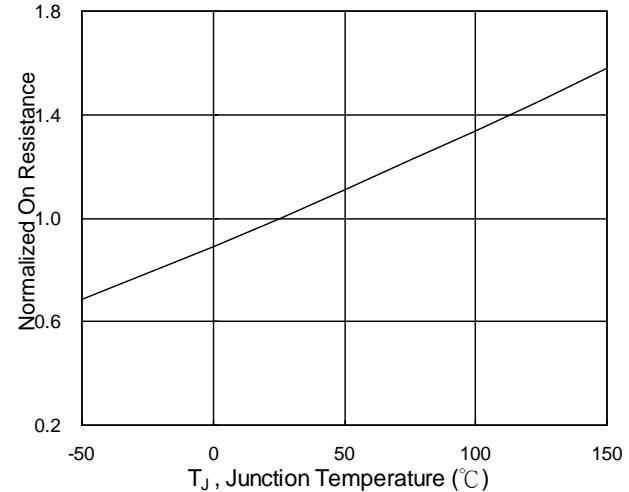
**Fig.3 Source Drain Forward Characteristics**



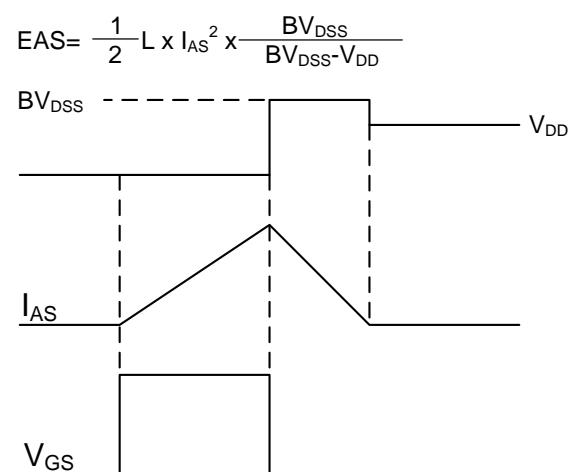
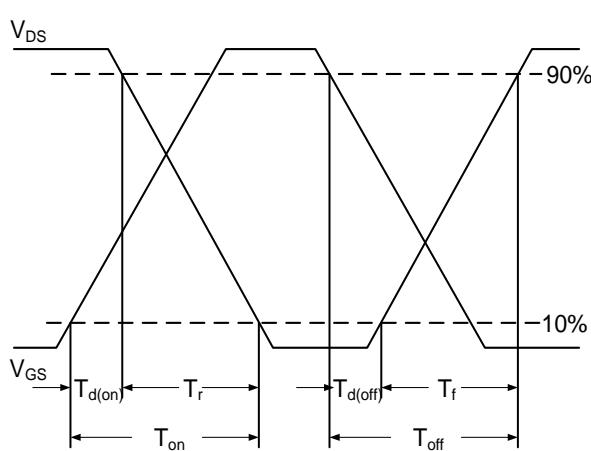
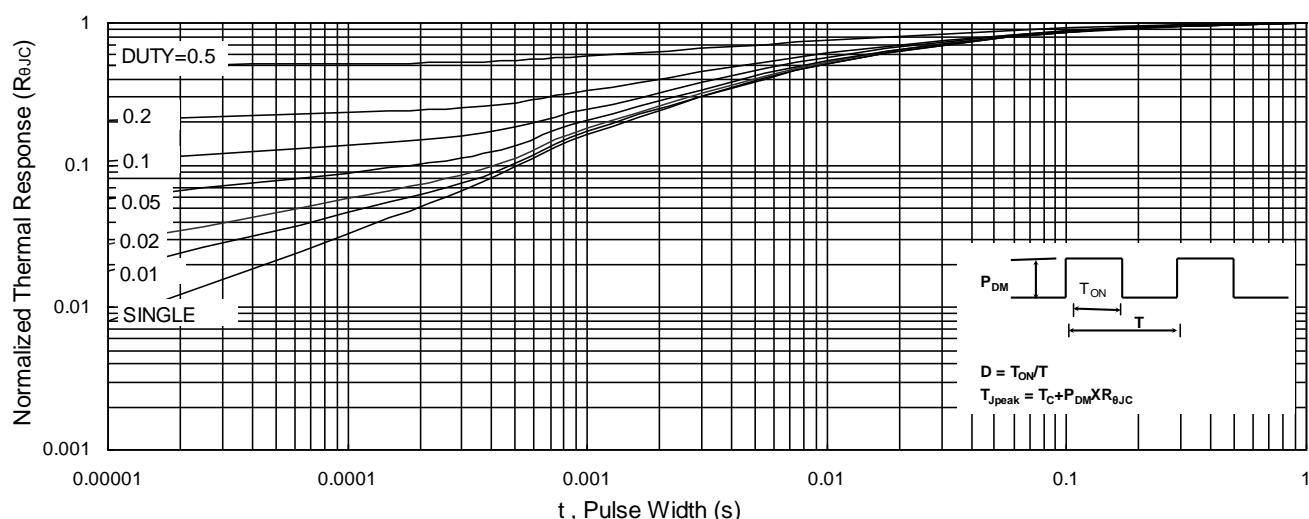
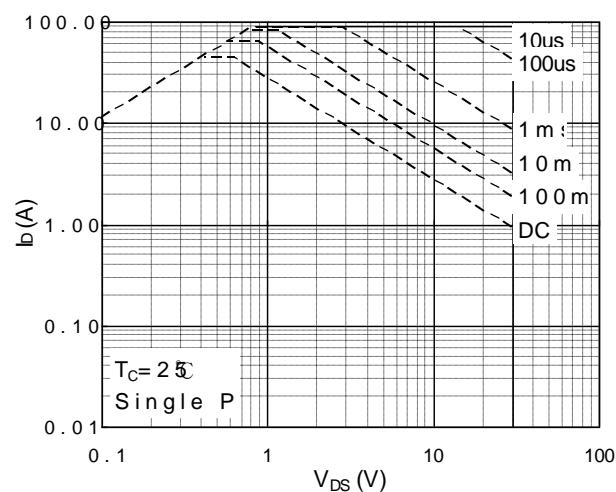
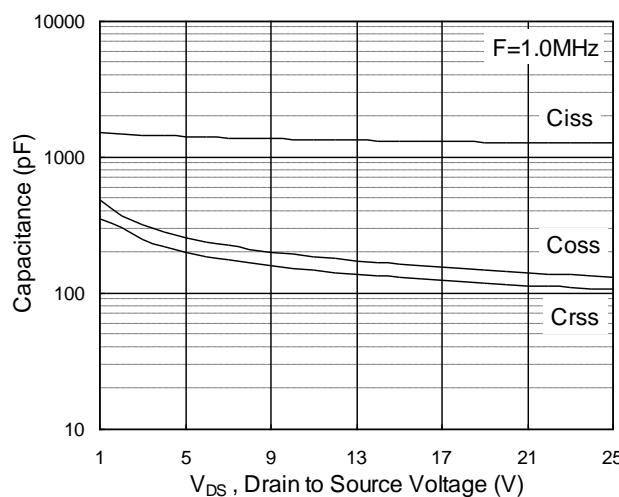
**Fig.4 Gate-Charge Characteristics**

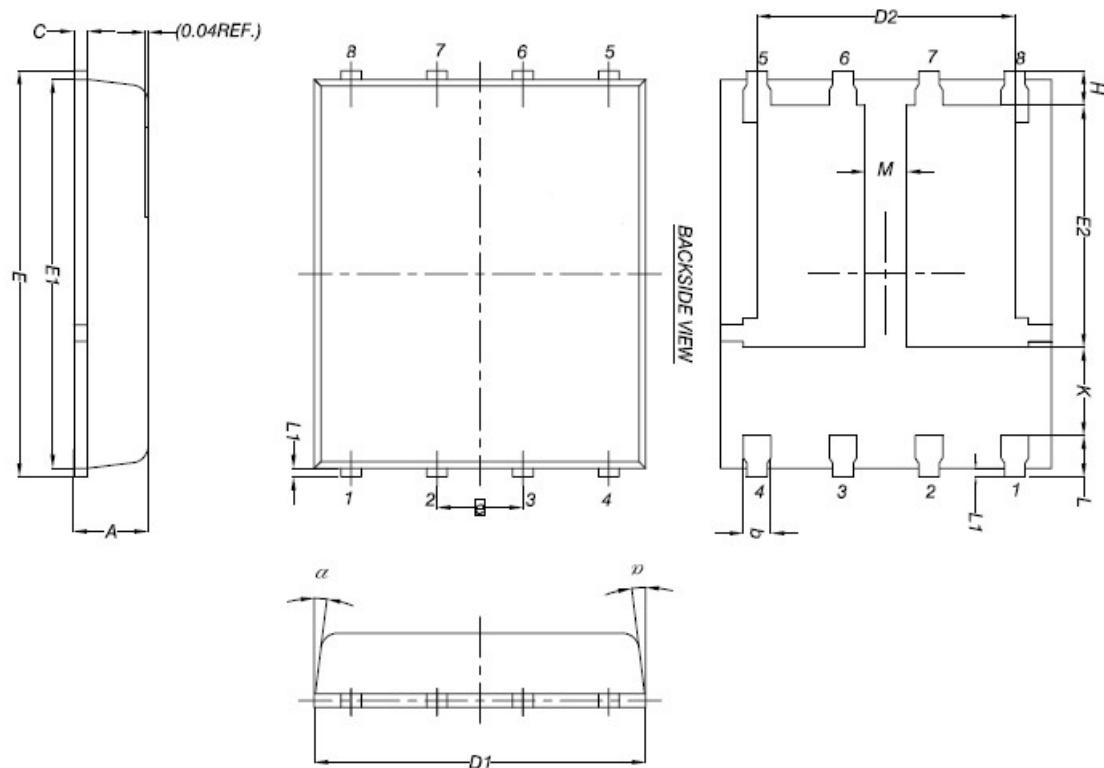


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**





SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.17	0.035	0.046
b	0.33	0.51	0.013	0.020
C	0.20	0.30	0.008	0.012
D1	4.80	5.20	0.189	0.205
D2	3.61	3.96	0.142	0.156
E	5.90	6.15	0.232	0.242
E1	5.70	5.85	0.224	0.230
E2	3.30	3.78	0.130	0.149
e	1.27 BSC		0.05 BSC	
H	0.38	0.61	0.015	0.024
K	1.10	---	0.043	---
L	0.38	0.61	0.015	0.024
L1	0.05	0.25	0.002	0.010
M	0.50	---	0.020	---
$\alpha$	0°	12°	0°	12°

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